

April 19 (Thu.)

9:30	<p>TA1: Advanced Packaging Chairperson:A. J. Babiarz (Asymtek) A. Okuno (Japan Rec)</p> <ol style="list-style-type: none">Market Trends in Die Product / MCM Applications (Invited) C. Bauer, TechLead / U.S.A.From CSP to WLP J. Simon, Technische Universtitat Berlin / GermanyPackaging Technology for Processor N. Shimizu, Fujitsu / JapanSuper Thin Packages for 3-Dimensional Assembly T. Kurihara, Shinko Electric Industries / JapanMethod for Production of Semiconductor Packaging N. Oyama, Japan Rec / JapanNew Concept of Low Cost Plastic Package for GHz Devices K. Seyama, M. Nishihara, H. Yamamoto, Fujitsu / Japan	<p>TB1: Substrates (1) Chairperson:Yu-J. Huang (I-Shou University) S. Uegaki (Kyocera)</p> <ol style="list-style-type: none">Microwave LTCC Technology Using Photo Patterned Conductors (Invited) P. Barnwell, Heraeus / U.K.New Generation Silver Based LTCC System for Wireless Applications L. Chai, A. Shaikh, J. Henry, V. Stygar, Ferro / U.S.A.New LTCC Package for Microwave Application M. Tomisako, Kyocera / JapanPb-Free Thick Film Resistor Series Designed for both LTCC System and 96% Al₂O₃ Substrate C. Higuchi, Tanaka Kikinokogyo / JapanA Study on the Sintering Dynamics of Low Temperature Cofired Ceramics H. Zhenyu, M. Jusheng, Z. Guangneng, X. Zhonghua, H. Le, Tsinghua University / ChinaInfluence of Sintering Atmosphere on Glass Ceramics/Cu X. Zhonghua, M. Jusheng, W. Yonggang, H. Zhenyu, H. Le, Tsinghua University / China	<p>TC1: Plating & Substrates (2) Chairperson:E.J. Vardaman (TechSearch International) Y. Fukuoka (DT Circuit Technology)</p> <ol style="list-style-type: none">Via-filling Using Copper Electroplating for Build-up Multilayer Board S. Miura, H. Honma, Kanto Gakuin University / JapanThe Hydrazine Reduced EN as the Alternative Process for Selective Deposition K. Tashiro, Y. Takada, K. Ishikawa, H. Honma, Kanto Gakuin University / JapanElectroless Gold Plating Technology for Usage of Ascorbic Acid as Reducing Agent N. Hattori, Okuno Chemical Industries / JapanOptimization of Black Oxide Coating Thickness as Adhesion Promoter for Copper Substrate J.-K. Kim, M. Lebbai, W. K. Szeto, Hong Kong University of Science & Technology / Hong KongEnvironmentally Friendly Printed Wiring Board (glass-epoxy laminate) without Halogen-type and Phosphorus-type Flame Retardants M. Iji, Y. Kikuchi, NEC / JapanExcellent Reliability Epoxy Adhesive Sheet for High Density Substrate and New Halogen-free Alternative Materials N. Ogawa, Hitachi Chemical / Japan
12:00	LUNCH TIME		
13:00	<p>TA2: Thermal Management Chairperson:C. Drevon (Alcatel Space Industries) S. Kitajo (NEC)</p> <ol style="list-style-type: none">The Role of Soft Computing in Thermal Design of Compact Electronic Equipment (Invited) W. Nakayama, ThermTech International / JapanDevelopment of the MEMS Methodology to Micro Heat Sinks M.-H. Tseng, C.-Y. Wang, H.-C. Chien, C.-H. Chu, Industrial Technology Research Institute / TaiwanMetal-graphite Composite Heat Spreaders having Super High Thermal Conductivity and Low Thermal Expansion Coefficient C. Kawai, Y. Hirose, T. Tomikawa, Sumitomo Electric Industries / JapanConventional Forced-air Cooling Scheme with Non-conventional Approaches D. Wang, K. Muller, NCR / U.S.A.Modified Pad Patterns for CPW Millimeter-wave Flip-chip J.-S. Kim, Y.-S. Chae, Y.-S. Yoon, J.-K. Rhee, H.-C. Kwon*, H.-S. Park**, Dongguk University, *GIO Communications, **Hankyong National University / Korea	<p>TB2: Emerging Technologies Chairperson:S. Denda (Nagano Institute of Technology) H. Tomimuro (NTT Electronics)</p> <ol style="list-style-type: none">BGA to CSP to Flip Chip - Manufacturing Issues (Invited) G. Caswell, J. Partridge, Xetel / U.S.A.A Wafer Level Chip Size Package with a Printed Stress Compliant Layer H. Hozoji, Y. Yamaguchi, H. Tenmei, S. Tsunoda, M. Minagawa, N. Kanda, Y. Morishita*, T. Tanaka*, Y. Yano*, Hitachi, *Hitachi Chemical / JapanWafer Level Electroless Ni/Au Plating Copper Pad Metallization - A Solution for Wire Bonding and Flip Chip E. Zakel, T. Teutsch, F. Koster, PacTech / GermanyAdvanced Packaging Trends in Wireless Products J. Vardaman, TechSearch International / U.S.A.Multichip Packaging for Mobile Telephony C. Bauer, TechLead / U.S.A.	<p>TC2: Interconnection (1) Chairperson:R. Nickerson (AST Products) K. Tsukamoto (Matsushita Electric Industrial)</p> <ol style="list-style-type: none">Cross-sectional Analysis of Anisotropically Conductive Film Connection Using Transmission Electron Microscopy and Finite Element Method S. Tsuji, K. Tsujimoto, K. Tanahashi, H. Nishida, K. Kuroda*, H. Saka*, IBM Japan, *Nagoya University / JapanConductivity Model for Metal Coated Polymer Particles Used in Anisotropically Conductive Adhesives J. Maattanen, P. Palm, A. Tuominen*, Elcoteq Network, *Tampere University of Technology / FinlandAdvances in Fast Underfill of Flip Chips A. Babiarz, H. Quinones, Asymtek / U.S.A.Ultrasonic Flip-chip Bonding Technology Using Preformed Underfill-resin M. Kimura, T. Iwasaki, S. Yamada, Y. Hatanaka, H. Fujioka, N. Ueda, Mitsubishi Electric / JapanDevelopment of New Encapsulant for IC Packages O. Suzuki, Namics / Japan
15:05	COFFEE BREAK		
15:25	<p>TA3: Optoelectronics Chairperson:A. Chandrasekhar (IMEC vzw) Y. Ando (Fujikura)</p> <ol style="list-style-type: none">Scalable Film Optical Link Multi-chip-module(S-FOLM) - Structure and Process Design - T. Yoshimura, K. Kumai, T. Mikawa, O. Ibaragi, Association of Super-Advanced Electronics Technologies (ASET) / JapanOpto-electronic Chip-on-film Packaging Technology Using Optical Waveguide Films with Low Coefficients of Thermal Expansion S. Ishibashi, NTT / JapanGiga- : A Low-cost and Compact Parallel Optical Link Module for Very Short Reach Interconnect T. Sakamoto, N. Tanaka, N. Kukutsu, NTT / JapanDevelopment of an Optical Active Connector for LAN N. Tanaka, N. Iwasaki, M. Yanagibashi, NTT / JapanDiamond Package for 10Gbps EA Driver IC S. Ooe, Y. Yamamoto, A. Nakamura, T. Tomikawa, T. Imai, N. Shiga, S. Yamanaka, Sumitomo Electric Industries / Japan	<p>TB3: Pb-free Solders and Environmentally Friendly Materials Chairperson:D. Frear (Motorola) H. Sawai (Oki Electric Industry)</p> <ol style="list-style-type: none">Resemblance of Fracture by Mechanical Stress and Degradation by Thermal Stress in Lead-free Solder Y. Takenaka, M. Tanigami, K. Sasaki, M. Hiramio, Omron / JapanThermal Fatigue Behavior of CSP Solder Joint with Sn-Ag Lead-free Solders under Thermal Cycle Condition I. Shohji, Gunma University / JapanA Comparative Analysis of Lead-free Solder Bumping for Aluminum and Copper Metallized Wafers G. Vishwanadam, V. Kripesh, S. Lim, T.P. Song, Institute of Microelectronics / SingaporeMechanical Property and Life-time Simulation for Lead-free Solder Y. Kaga, NEC / JapanFluxless Reflowing on SnAg and High-PbSn Solder Bumps H. Matsuki, Fujitsu / Japan	<p>TC3: Materials (1) Chairperson:A. Shaikh (Ferro) F. Uchikiba (TDK)</p> <ol style="list-style-type: none">Applications of Newly Developed Block Co-Polyimides to Microelectronic Packaging Processes S. Matsumoto, PI R&D / JapanCure Behaviour and Interfacial Adhesion of a Photo-sensitive BCB K.C. Chan, C.P. Cheong, G.N. Lee, Microfab Technology / SingaporeThe Research of Conduction Mechanism of the Conductive Channels of the Thick Film Resistor O. Toyozumi, I. Kaneko, Musashi Institute of Technology / JapanPotential Application of SmSx Material in Microelectronics P. Miodushevsky, Powerco S.p.A / ItalyA Study on the Relationships between Electrical Contact Resistance and Current Flow in Electrical Sliding Contacts M. Taniguchi, H. Ishida, T. Takagi, Tohoku Bunka Gakuen University / Japan
17:30			